Special Issue

State-of-the-Art 3D Imaging, Processing and Display Technologies

Message from the Guest Editors

Three-dimensional technologies have become an integral part of today's fundamental applications in immersive media, augmented reality, virtual reality, extended reality, games and entertainment, security, autonomous vehicles, and robotics, as well as in various enhancements of computer vision. This Special Issue covers selected outcomes of state-of-the-art research, ranging from 3D acquisition to its processing and applications. This Special Issue also serves as a comprehensive review on state-of-the-art 3D imaging techniques, their processing and display, and provides a broad insight into the development of various disciplines.

Guest Editors

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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